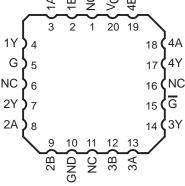
- Meets EIA Standards RS-422-A, RS-423-A, RS-485, and CCITT V.11
- Designed to Operate With Pulse Durations as Short as 20 ns
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- Input Sensitivity . . . ±200 mV
- Low-Power Consumption . . . 20 mA Max
- Open-Circuit Fail-Safe Design
- Pin Compatible With SN75173 and AM26LS32

description

The SN55LBC173 is a monolithic quadruple differential line receiver with 3-state outputs designed to meet the requirements of the EIA standards RS-422-A, RS-423-A, RS-485, and CCITT V.11. This device is optimized for balanced multipoint bus transmission at data rates up to and exceeding 10 million bits per second. The four receivers share two ORed enable inputs, one active when high, the other active when low. Each receiver features high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ±200 mV over a common-mode input voltage range of 12 V to -7 V. Fail-safe design ensures that if the inputs are open circuited, the output is always high. The SN55LBC173 is designed using the Texas Instruments proprietary LinBiCMOS[™] technology that provides low power consumption, high switching speeds, and robustness.

ΊO	J OR W PACKAGE (TOP VIEW)								
1B [1A [1Y [2Y [2A [2B [GND [1 2 3 4 5 6 7 8		16 15 14 13 12 11 10 9] V(] 4E] 4/] 4)] 3)] 3/] 3E	A ((A				
		ACK P VII	(AGE EW)	E					
4 4 4	2 1B	NC 1	20 20	19	18 4	Ļ			

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NC - No internal connection

This device offers optimum performance when used with the SN55LBC172M quadruple line driver. The SN55LBC173 is available in the 16-pin CDIP (J), the 16-pin CPAK (W), or the 20-pin LCCC (FK) packages.

The SN55LBC173 is characterized over the military temperature range of -55°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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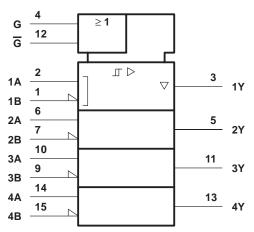
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FUNCTION TABLE (each receiver)								
DIFFERENTIAL INPUTS	ENA	BLES	OUTPUT					
A-B	G	G	Y					
$V_{ID} \ge 0.2 V$	H	X	H					
	X	L	H					
$-0.2 V < V_{ID} < 0.2 V$	H	X	?					
	X	L	?					
$V_{ID} \leq -0.2 V$	H	X	L					
	X	L	L					
Х	L	Н	Z					
Open circuit	H	X	H					
	X	L	H					

H = high level, L = low level, X = irrelevant,

Z = high impedance (off), ? = indeterminate

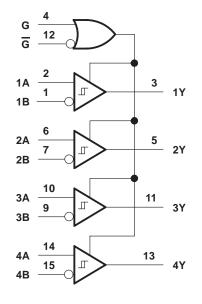
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the J or W package.

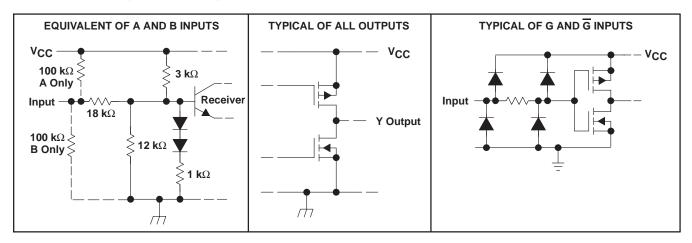
logic diagram (positive logic)





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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} (see Note 1)	
Input voltage, VI (A or B inputs)	±25 V
Differential input voltage, VID (see Note 2)	±25 V
Data and control voltage range	0.3 V to 7 V
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–55°C to 125°C
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.

2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

DISSIPATION RATING TABLE									
PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 125°C POWER RATING						
FK	1375 mW	11.0 mW/°C	275 mW						
J	1375 mW	11.0 mW/°C	275 mW						
W	1000 mW	8.0 mW/°C	200 mW						

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
Common-mode input voltage, VIC				12	V
Differential input voltage, VID				±6	V
High-level input voltage, VIH	G inputs	2			V
Low-level input voltage, VIL				0.8	V
High-level output current, IOH				-8	mA
Low-level output current, IOL				16	mA
Operating free-air temperature, TA		-55		125	°C



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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER			т	MIN	TYP [†]	MAX	UNIT			
V_{IT+}	Positive-going input thre	shold voltage	$I_{O} = -8 \text{ mA}$					0.2	V	
V_{IT-}	Negative-going input thr	eshold voltage	I _O = 8 mA			-0.2			V	
V _{hys}	Hysteresis voltage (VIT	$+ - V_{IT} -)$					45		mV	
VIK	Enable input clamp volta	age	lı = – 18 mA				-0.9	-1.5	V	
Vон	High-level output voltage	e	V _{ID} = 200 mV,	I _{OH} = -8 mA	ł	3.5	4.5		V	
Vai	VOL Low-level output voltage		$V_{ID} = -200 \text{ mV},$	IOL = 8 mA			0.3	0.5	V	
VOL			$V_{ID} = -200 \text{ mV},$	I _{OL} = 8 mA,	T _A = 125°C			0.7	V	
IOZ	High-impedance-state o	utput current	$V_{O} = 0 V \text{ to } V_{CC}$					±20	μΑ	
		A or B inputs	V _{IH} = 12 V,	V _{CC} = 5 V,	Other inputs at 0 V		0.7	1		
			V _{IH} = 12 V,	$V_{CC} = 0 V,$	Other inputs at 0 V		0.8	1	mA	
tι	Bus input current		$V_{IH} = -7 V$,	V _{CC} = 5 V,	Other inputs at 0 V		-0.5	-0.8	ША	
			$V_{IH} = -7 V$,	$V_{CC} = 0 V,$	Other inputs at 0 V		-0.4	-0.8		
IIН	High-level input current		V _{IH} = 5 V					±20	μΑ	
ЦĽ	Low-level input current		V _{IL} = 0 V					-20	μA	
IOS	Short-circuit output curre	ent	$V_{O} = 0$				-80	-120	mA	
	Supply ourrent		Outputs enabled,	I _O = 0,	$V_{ID} = 5 V$		11	20	mA	
ICC	Supply current		Outputs disabled				0.9	1.4	шА	

[†] All typical values are at $V_{CC} = 5$ V and $T_A = 25^{\circ}C$.

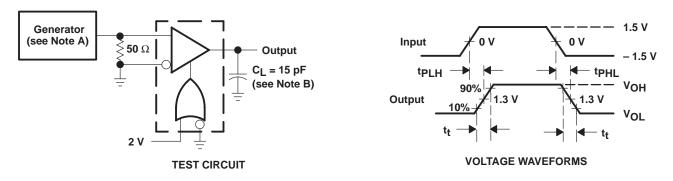
switching characteristics, V_{CC} = 5 V, C_L = 15 pF

	PARAMETER	TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT	
touu	Propagation delay time, high-to-low-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$	25°C	11	22	30	ns	
^t PHL	Propagation delay time, high-to-low-level output	See Figure 1	-55°C to 125°C	11		35	115	
tour	Propagation delay time, low-to-high-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$	25°C	11	22	35	ns	
^t PLH	Propagation delay time, tow-to-high-level output	See Figure 1	-55°C to 125°C	11		35	115	
+	Output anable time to bigh lovel	See Figure 2	25°C		17	40	20	
^t PZH	Output enable time to high level	See Figure 2	-55°C to 125°C			45	ns	
4		See Figure 2	25°C		18	30	ns	
^t PZL	Output enable time to low level	See Figure 3	-55°C to 125°C			35		
4	Output disable time from high lovel		25°C		30	40	ns	
^t PHZ	Output disable time from high level	See Figure 2	-55°C to 125°C			55		
4	Output dischle time from low level		25°C		25	40	~~	
^t PLZ	Output disable time from low level	See Figure 3	-55°C to 125°C			45	ns	
4		Cas Figure 4	25°C		0.5	6	ns	
t _{sk(p)} Pulse skew	Pulse skew (tpHL - tpLH)	See Figure 1	-55°C to 125°C			7		
t.	Transition time	See Figure 1	25°C		5	10	200	
tt			-55°C to 125°C			16	ns	



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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle \leq 50%, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .
 - B. CL includes probe and jig capacitance.

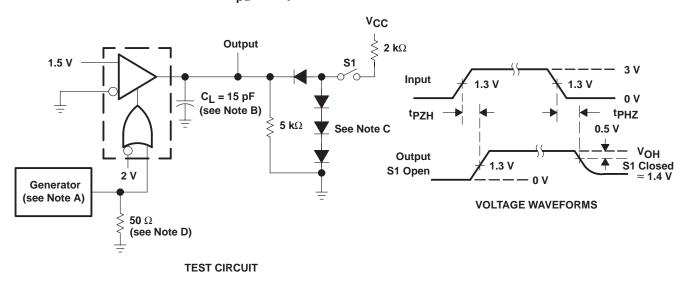


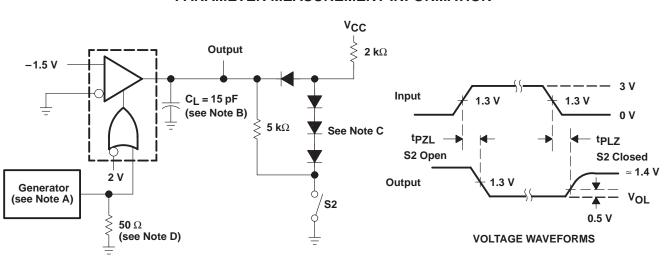
Figure 1. tpd and tt Test Circuit and Voltage Waveforms

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle \leq 50%, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .
 - B. C₁ includes probe and jig capacitance.
 - C. All diodes are 1N916 or equivalent.
 - D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 2. t_{PHZ} and t_{PZH} Test Circuit and Voltage Waveforms



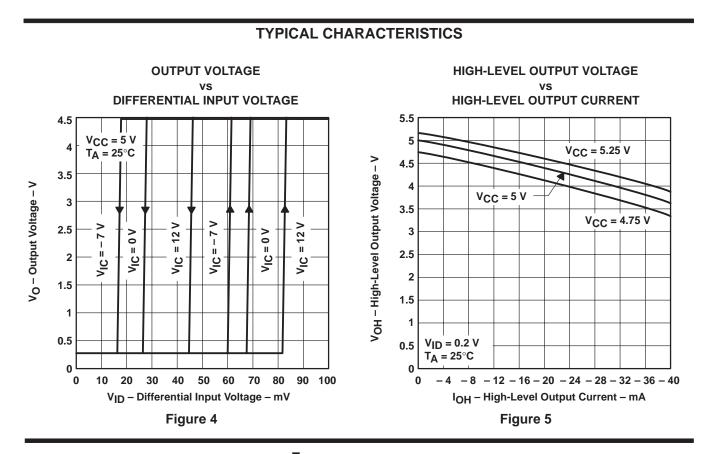
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TEST CIRCUIT

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle \leq 50%, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .
 - B. CL includes probe and jig capacitance.
 - C. All diodes are 1N916 or equivalent.
 - D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

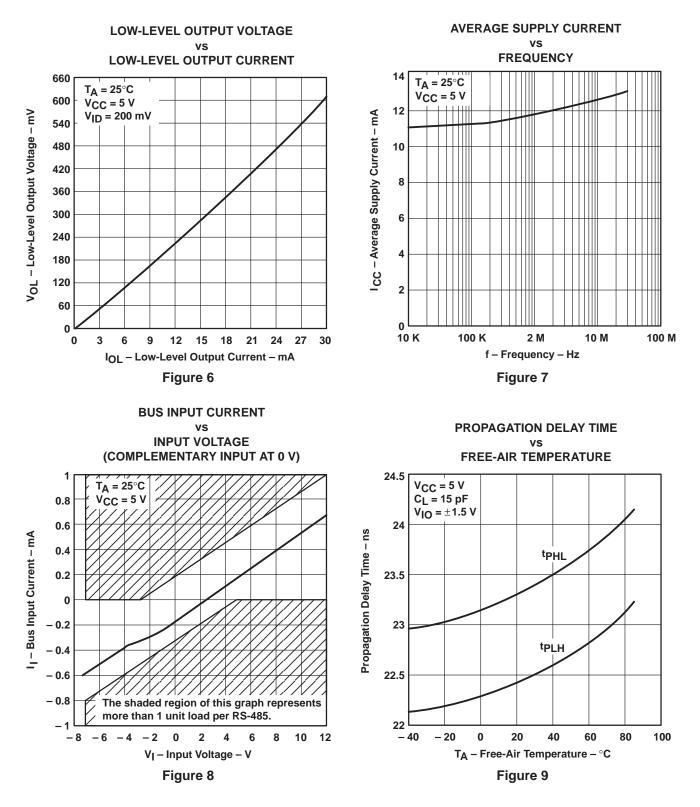
Figure 3. t_{PZL} and t_{PLZ} Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9076604Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9076604Q2A SNJ55 LBC173FK	Samples
5962-9076604QEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QE A SNJ55LBC173J	Samples
5962-9076604QFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QF A SNJ55LBC173W	Samples
SNJ55LBC173FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9076604Q2A SNJ55 LBC173FK	Samples
SNJ55LBC173J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QE A SNJ55LBC173J	Samples
SNJ55LBC173W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9076604QF A SNJ55LBC173W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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PACKAGE OPTION ADDENDUM

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN55LBC173 :

• Catalog : SN75LBC173

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

TEXAS INSTRUMENTS

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9-Aug-2022

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9076604Q2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9076604QFA	W	CFP	16	1	506.98	26.16	6220	NA
SNJ55LBC173FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ55LBC173W	W	CFP	16	1	506.98	26.16	6220	NA

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16



FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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